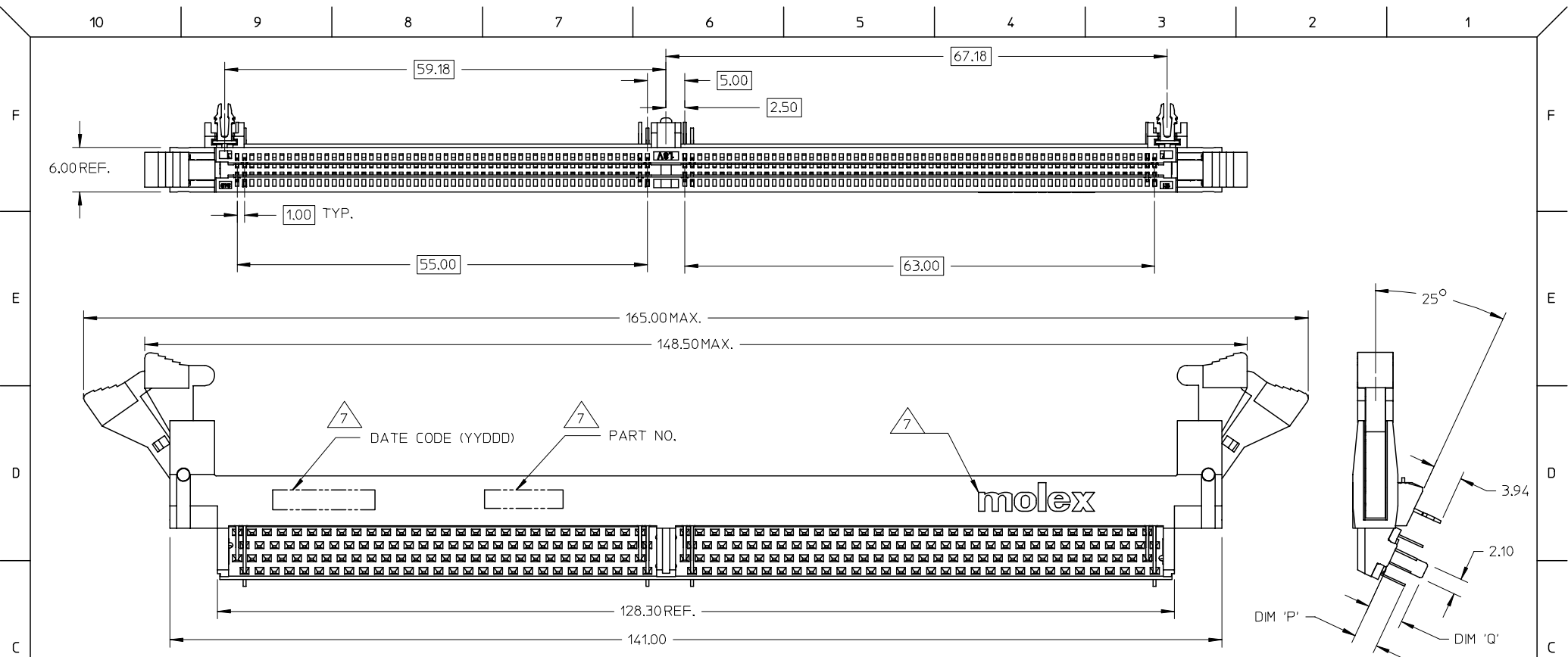
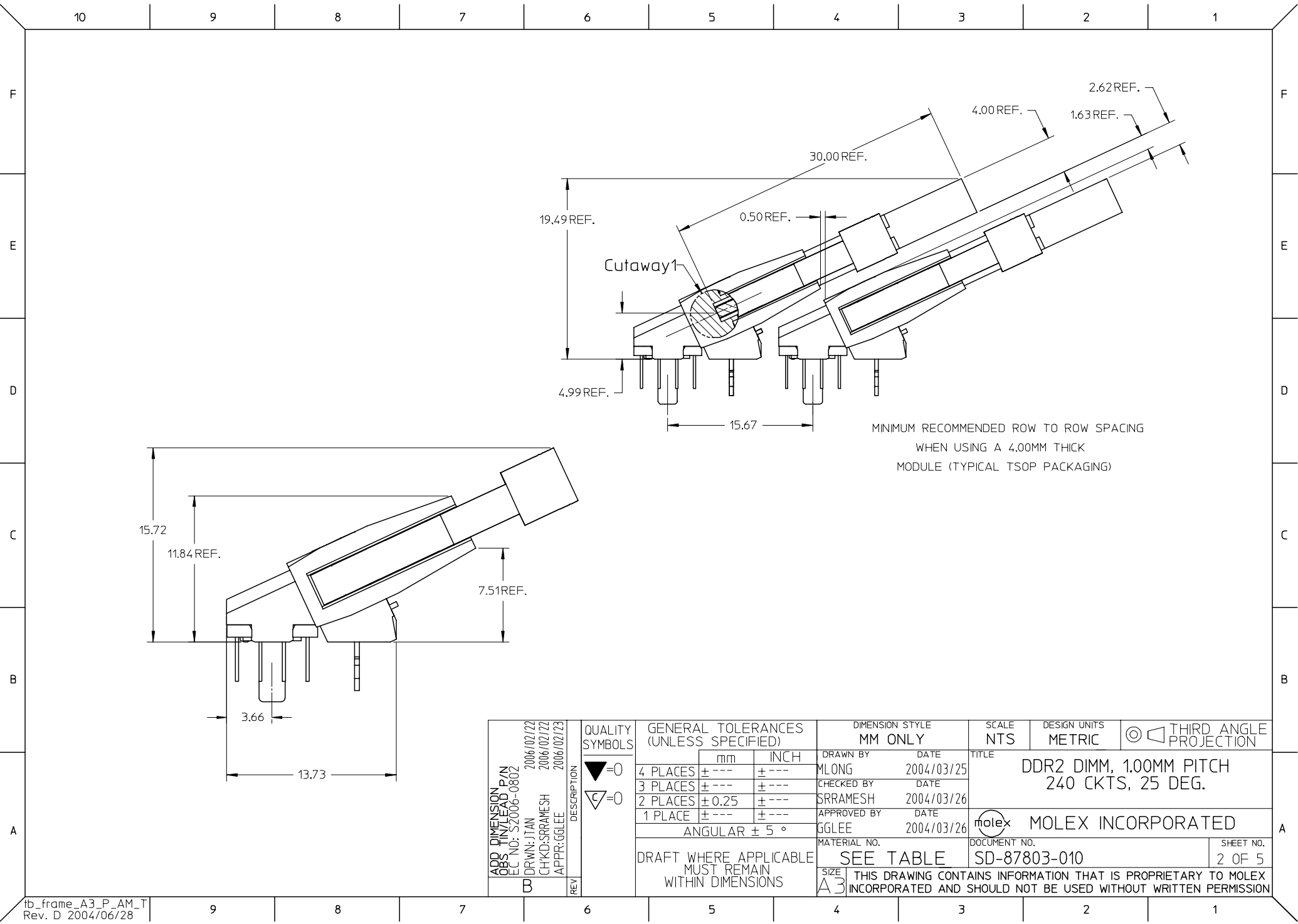




NOTES:

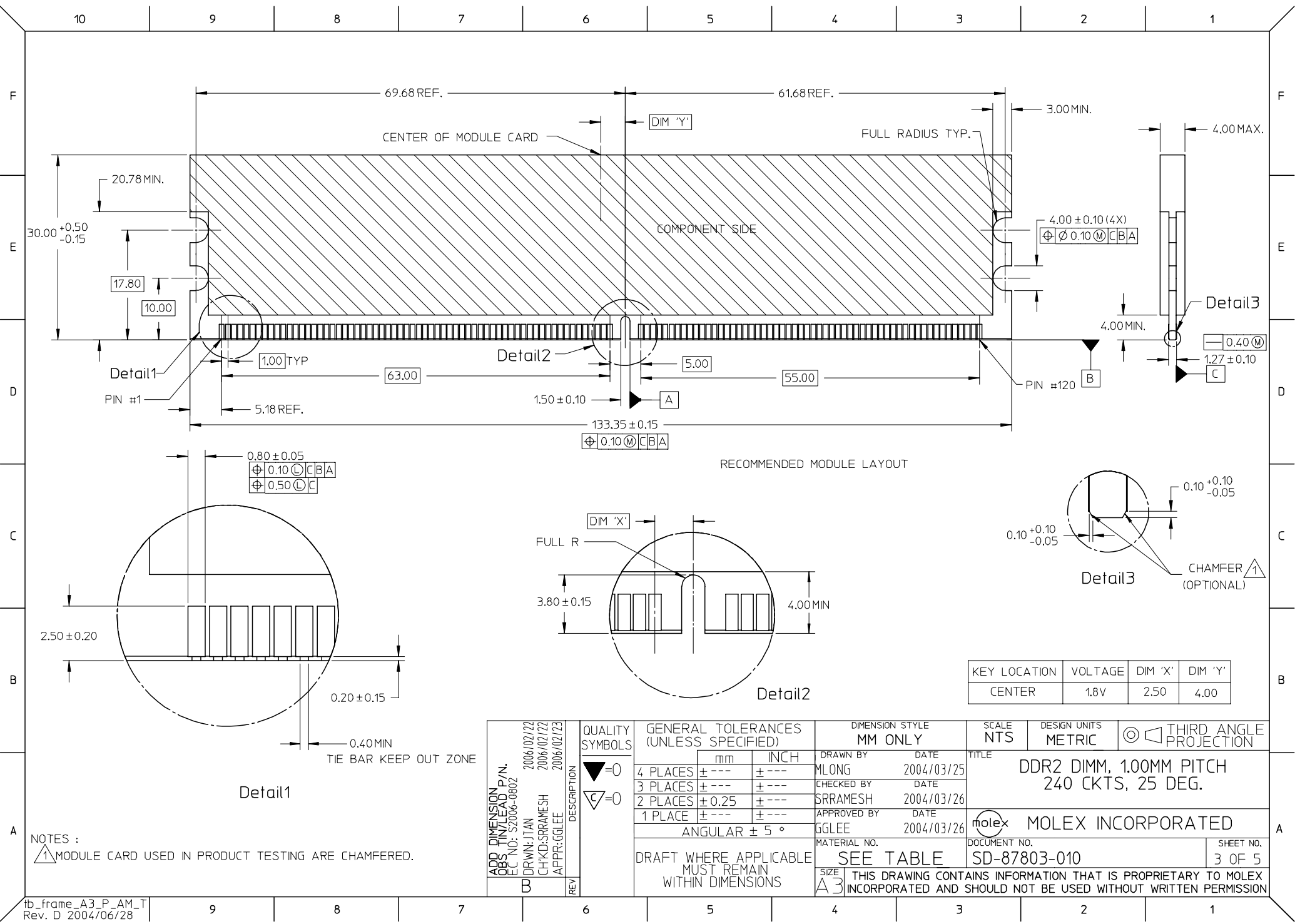
- MATERIALS : HOUSING AND BASEPLATE
 - LCP, GLASS FILLED, UL 94V-0, BLACK LATCH
 - HIGH TEMP. NYLON, GLASS FILLED, UL 94-0, NATURAL (OFF WHITE)TERMINALS AND FORKLICK - COPPER ALLOY
- PLATING : CONTACT AREA - SEE TABLE IN SHEET 5
SOLDERTAIL - SEE TABLE IN SHEET 5
- REFER TO PRODUCT SPECIFICATION, PS-87803-003 FOR PERFORMANCE SPECIFICATIONS.
- CARD SLOTS ACCEPTS 1.27±0.10 MM MODULE THICKNESS. (MEASURED OVER PC PADS)
- RECOMMENDED MODULE CARD LAYOUT SHALL BE AS PER JEDEC MO-237.
- PRODUCT IS PACKED IN TRAY.
- MOLEX LOGO, DATE CODE AND PART NUMBER INDICATED ON HOUSING.
- CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

ADD DIMENSION OBS THIS LEAD P/N EC NO: S2006-0802	2006/02/22 2006/02/22 2006/02/23	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION					
				4 PLACES 3 PLACES 2 PLACES 1 PLACE	mm INCH	± --- ± --- ± 0.25 ± ---	± --- ± --- ± --- ± ---	DRAWN BY MLONG	DATE 2004/03/25	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.					
								CHECKED BY SRRAMESH	DATE 2004/03/26						
								APPROVED BY GGLEE	DATE 2004/03/26						
								ANGULAR ± 5 °		MOLEX MOLEX INCORPORATED					
										MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
										SEE TABLE		SD-87803-010		1 OF 5	
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION													



MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 4.00MM THICK
MODULE (TYPICAL TSOP PACKAGING)

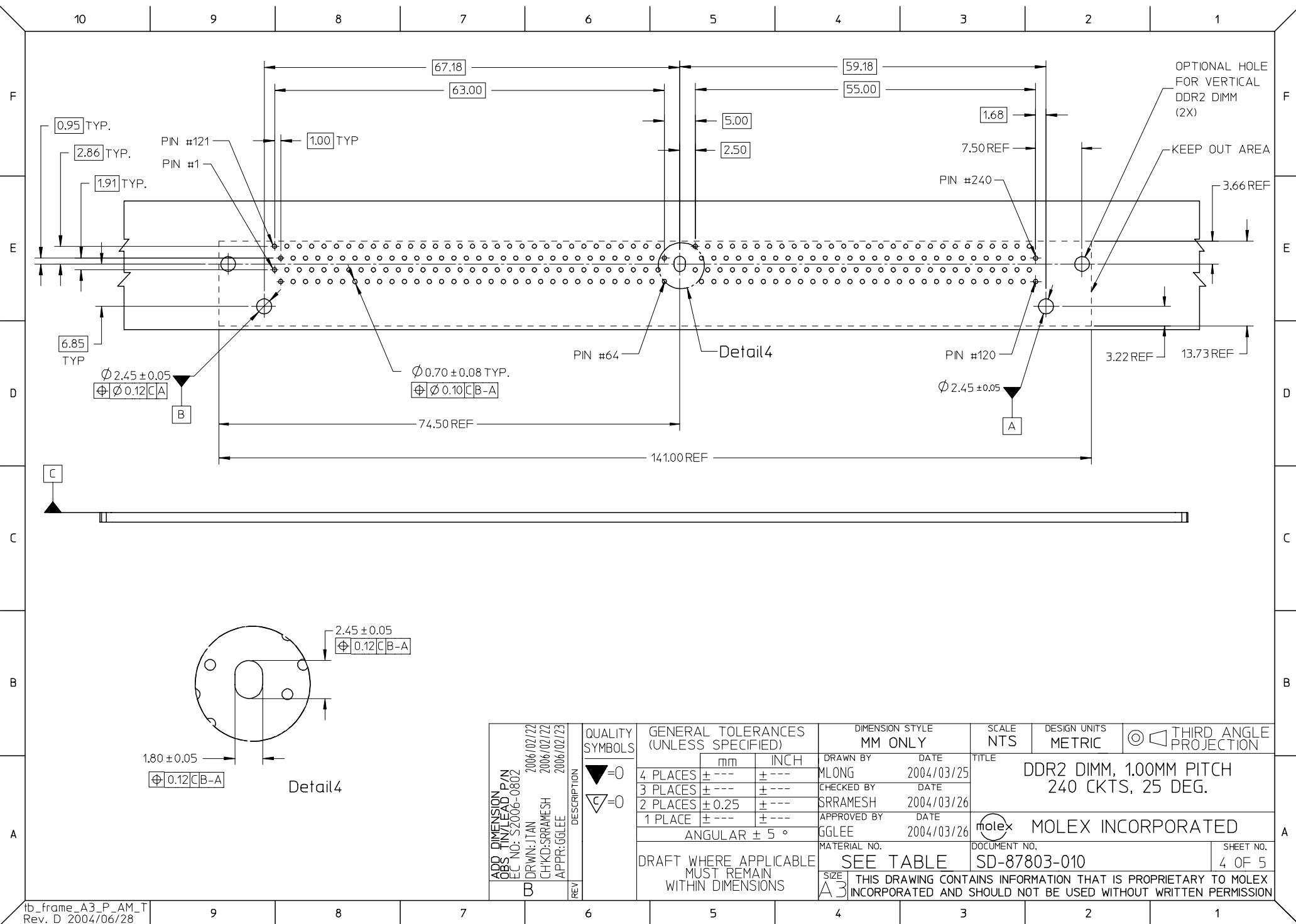
ADD DIMENSION OBS. TIN/LEAD P/N EC NO: S2006-0802	REV	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
				mm	INCH	DRAWN BY	DATE	TITLE					
				4 PLACES ± --- ± ---	MLONG	2004/03/25	DDR2 DIMM, 1.00MM PITCH						
				3 PLACES ± --- ± ---	CHECKED BY	DATE	240 CKTS, 25 DEG.						
				2 PLACES ± 0.25 ± ---	SRRAMESH	2004/03/26							
B				1 PLACE ± --- ± ---	APPROVED BY	DATE	MOLEX MOLEX INCORPORATED						
				GGLEE	2004/03/26								
				ANGULAR ± 5 °		MATERIAL NO.	DOCUMENT NO.	SHEET NO.					
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	SD-87803-010	2 OF 5					
						SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



KEY LOCATION	VOLTAGE	DIM 'X'	DIM 'Y'
CENTER	1.8V	2.50	4.00

ADD DIMENSION OBS. TIN/LEAD P/N. EC NO: S2006-0802	2006/02/22 DRWN:JTAN 2006/02/22 CHKD:SRRAMESH 2006/02/23 APPR:GGLLEE	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
						DRAWN BY MLONG		DATE 2004/03/25		TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.			
						CHECKED BY SRRAMESH		DATE 2004/03/26					
						APPROVED BY GGLLEE		DATE 2004/03/26		MOLEX MOLEX INCORPORATED			
				ANGULAR ± 5 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-87803-010		3 OF 5			
						SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

NOTES :
1 MODULE CARD USED IN PRODUCT TESTING ARE CHAMFERED.



PART NO.	VOLTAGE KEY	DIM 'P'	DIM 'Q'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING	SOLDERTAIL PLATING	LUBRICATION
87803-0002	1.8V	2.79	3.18	1.57	0.38uM/ 15u" GOLD OVER	2.54uM/ 100u" MIN. TIN OVER 1.27uM/ 50u" MIN NICKEL	NO
87803-0022					YES		
87803-0012		3.18	4.83	2.36	1.27uM/ 50u" MIN NICKEL		NO
87803-0032					YES		
87803-0102		2.79	3.18	1.57	0.76uM/ 30u" GOLD OVER 1.27uM/ 50u" MIN NICKEL		NO
87803-0122							YES
87803-0112		3.18	4.83	2.36			NO
87803-0132							YES

[illegible]